

ABSTRACT

The purpose of the present invention is to provide a polishing pad which includes a polishing layer having a triple phase separation structure and has a high polishing rate and excellent planarization characteristics, while being capable of suppressing the occurrence of scratches. A polishing pad of the present invention comprises a polishing layer, and the polishing layer is formed of a reaction cured body of a polyurethane-forming raw material composition that contains: an isocyanate-terminated prepolymer (A) which is obtained by reacting a prepolymer-forming raw material composition (a) that contains an isocyanate component and a polyester polyol; an isocyanate-terminated prepolymer (B) which is obtained by reacting a prepolymer-forming raw material composition (b) that contains an isocyanate component and a polyether polyol; and a chain extender. The polyether polyol contains a polyether polyol (C) that has a number average molecular weight of 1000 or less and a polyether polyol (D) that has a number average molecular weight of 1900 or more. The reaction cured body has a triple phase separation structure.